

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT6740196

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
ROHIT TIRUMALA	06/01/2021
MIGUEL SALCEDO	05/11/2021
DONALD HUMBERT	05/07/2021
RECEIVING PARTY DATA	
Name:	MICROCHIP TECHNOLOGY INCORPORATED
Street Address:	2355 WEST CHANDLER BLVD
City:	CHANDLER
State/Country:	ARIZONA
Postal Code:	85224-6199
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17336504
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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ATTORNEY DOCKET NUMBER:	0026725.0000104
NAME OF SUBMITTER:	RYAN M. CORBETT
SIGNATURE:	/Ryan M. Corbett/
DATE SIGNED:	06/02/2021
Total Attachments: 4	
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ASSIGNMENT

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we, the below signed inventors of record, hereby assign to:

MICROCHIP TECHNOLOGY INCORPORATED
2355 WEST CHANDLER BLVD.
CHANDLER, AZ 85224-6199

and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and interest throughout the world in the inventions and improvements which are the subject of the United States Patent Application submitted herewith, entitled:

"METHOD AND APPARATUS FOR MODULATING AMPLIFIER SUPPLY VOLTAGE FOR REDUCING POWER DISSIPATION"

this assignment including said application, any and all United States and foreign patents, utility models, design registrations, inventor's certificates and other similar rights granted for any of said inventions or improvements, and the right to claim priority based on the filing date of said application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and we authorize the Assignee to apply in all countries in our names, or in its own name, for patents, utility models, design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements; and we agree for ourselves and our heirs, legal representatives and assigns, without further compensation to perform such lawful acts and to sign such further applications, assignments, Preliminary Statements and other lawful documents as the Assignee may reasonably request to effectuate fully this assignment.

IN WITNESS THEREOF, we hereby set our hand, date of signature and place of signature as indicated below.

Full Name of First Inventor: Rohit Tirumala

Residence: Sunnyvale, California, United States

Citizenship: United States

Post Office Address: 1109 Lily Ave., Sunnyvale, CA 94086

Signature of First Inventor

Date of Signature

Full Name of Second Inventor: Miguel Salcedo

Residence: Watsonville, California, United States

Citizenship: United States

Post Office Address: 311 Main St., #42, Watsonville, CA 65076



Signature of Second Inventor

5/11/2021

Date of Signature

Full Name of Third Inventor: Donald Humbert

Residence: Santa Clara, California, United States

Citizenship: United States

Post Office Address: 3964 Rivermark Plaza, #149, Santa Clara, CA 65054

Signature of Third Inventor

Date of Signature

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CHANDLER, AZ 85224-6199

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Residence: Sunnyvale, California, United States

Citizenship: United States

Post Office Address: 1109 Lily Ave., Sunnyvale, CA 94086



Signature of First Inventor

6/1/2021

Date of Signature

Full Name of Second Inventor: Miguel Salcedo

Residence: Watsonville, California, United States

Citizenship: United States

Post Office Address: 311 Main St., #42, Watsonville, CA 95076

Signature of Second Inventor


Date of Signature

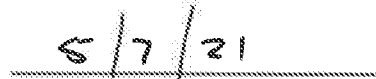
Full Name of Third Inventor: Donald Humbert

Residence: Santa Clara, California, United States

Citizenship: United States

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Signature of Third Inventor


Date of Signature